Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-17. (Canceled)

18. (Currently Amended) ~~Method~~ A method for recording data by means of an array of micro-tips arranged in a plane facing a memory ~~support,~~ support ~~comprising~~ including a stack of thin layers with at least one deformable memory layer, the method ~~comprising~~ comprising:

_____data recording by selective actuation of the micro-tips, ~~wherein,~~ the micro-tips being fixed directly onto ~~one and the same~~one and the same support ~~substrate,~~substrate; ~~the method comprises~~

_____bringing the array of micro-tips and the memory support into contact with a predetermined pressure, which is insufficient to cause a deformation representative of a data to be recorded, before the selective actuation of the micro-tips for data recording, said pressure enabling the dispersion of ~~the dimensions~~ heights of the micro-tips of the array of micro-tips to be absorbed by the deformable memory layer.

19. (Currently Amended) ~~Method~~ The method according to claim 18, wherein data recording is of electric type.

20. (Currently Amended) ~~Method~~ The method according to claim 18, wherein data recording is of thermal type.

21. (Canceled)

22. (Currently Amended) ~~Recording~~ A recording device for implementation of the method according to claim 18, ~~comprising~~ comprising:

~~an array of micro-tips arranged in a plane facing a memory support, comprising a stack of thin layers with at least one deformable memory layer,~~ means for absorbing the dispersion of the ~~dimensions~~ heights of the micro-tips of the ~~array~~ array; and

means for recording by the selective actuation of the micro-tips,

wherein the deformable memory layer constitutes said means for absorbing when the memory support and the array of micro-tips are brought into contact, at said predetermined pressure, which is insufficient to cause a deformation representative of a data to be recorded,

the micro-tips, having an apex of nanometric dimension, being fixed directly onto one and the same support substrate.

23. (Currently Amended) ~~Device~~ The device according to claim 22, wherein the memory layer is deposited on a flexible layer deposited on the substrate.

24. (Currently Amended) ~~Device~~ The device according to claim 23, wherein the flexible layer is made of polymer.

25. (Currently Amended) ~~Device~~ The device according to claim 24, wherein the flexible layer is made of photoresist.

26. (Currently Amended) ~~Device~~ The device according to claim 23, wherein the flexible layer is a glue of controlled hardness.

27. (Currently Amended) ~~Device~~ The device according to claim 23, wherein the flexible layer is made of elastomer silicone.

28. (Currently Amended) ~~Device~~ The device according to claim 23, wherein the flexible layer has a thickness of ~~about~~ a few micrometers.

29. (Currently Amended) ~~Device~~ The device according to claim 23, wherein the flexible layer is conducting.

30. (Currently Amended) ~~Device~~ The device according to claim 23, further ~~comprising~~ comprising:

_____an additional conducting layer between the memory layer and the flexible layer.

31. (Currently Amended) ~~Device~~ The device according to claim 22, wherein the memory layer has a thickness of less than one micrometer.

32. (Currently Amended) ~~Device~~ The device according to claim 22, further ~~comprising~~ comprising:

_____an interface layer with the micro-tips, covering the memory layer.

33. (Currently Amended) ~~Device~~ The device according to claim 22, wherein the substrate is made of silicon.

34. (Currently Amended) ~~Device~~ The device according to claim 22, wherein the substrate is made of plastic material with a thickness of less than one millimeter.